

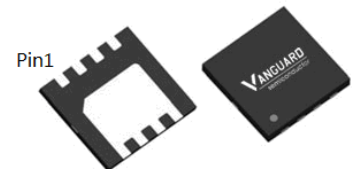
Features

- N-Channel, 3.3V Logic Level Control
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=3.3V$
- Fast Switching
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant

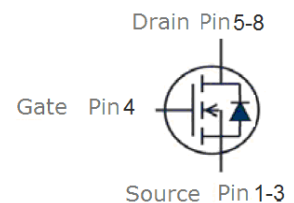


| | | |
|-------------------------------|-----|------------|
| V_{DS} | 20 | V |
| $R_{DS(on),TYP}@ V_{GS}=4.5V$ | 3.6 | m Ω |
| $R_{DS(on),TYP}@ V_{GS}=3.3V$ | 4.2 | m Ω |
| I_D | 60 | A |

TDFN3.3x3.3



| Part ID | Package Type | Marking | Tape and reel information |
|-------------|--------------|---------|---------------------------|
| VSB003N02LS | TDFN3.3x3.3 | 003N02L | 5000pcs/Reel |



Maximum ratings, at $T_j=25^\circ\text{C}$, unless otherwise specified

| Symbol | Parameter | Rating | Unit |
|---------------|---|-------------------------------|------------------|
| $V_{(BR)DSS}$ | Drain-Source breakdown voltage | 20 | V |
| I_S | Diode continuous forward current | $T_C=25^\circ\text{C}$ 60 | A |
| I_D | Continuous drain current@ $V_{GS}=10V$ | $T_C=25^\circ\text{C}$ 60 | A |
| | | $T_C=100^\circ\text{C}$ 38 | A |
| I_{DM} | Pulse drain current tested ① | $T_C=25^\circ\text{C}$ 240 | A |
| EAS | Avalanche energy, single pulsed ② | 33.75 | mJ |
| P_D | Maximum power dissipation | $T_C=25^\circ\text{C}$ 31 | W |
| V_{GS} | Gate-Source voltage | ± 8 | V |
| $T_{STG} T_J$ | Storage and operating temperature range | -55 to 150 | $^\circ\text{C}$ |

Thermal Characteristics

| Symbol | Parameter | Typical | Unit |
|-----------------|-------------------------------------|---------|--------------------|
| $R_{\theta JC}$ | Thermal Resistance-Junction to Case | 4.0 | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient | 40 | $^\circ\text{C/W}$ |

Typical Characteristics

| Symbol | Parameter | Condition | Min. | Typ. | Max. | Unit |
|---|--|---|------|------|------|------|
| Static Electrical Characteristics @ T_c = 25°C (unless otherwise stated) | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 20 | -- | -- | V |
| I _{DSS} | Zero Gate Voltage Drain Current(T _c =25°C) | V _{DS} =20V, V _{GS} =0V | -- | -- | 1 | μA |
| | Zero Gate Voltage Drain Current(T _c =125°C) | V _{DS} =20V, V _{GS} =0V | -- | -- | 100 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =±8V, V _{DS} =0V | -- | -- | ±100 | nA |
| V _{GS(TH)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 0.3 | 0.6 | 1.2 | V |
| R _{DS(ON)} | Drain-Source On-State Resistance ^③ | V _{GS} =4.5V, I _D =20A | -- | 3.6 | 5 | mΩ |
| R _{DS(ON)} | Drain-Source On-State Resistance ^③ | V _{GS} =3.3V, I _D =15A | -- | 4.2 | 6 | mΩ |
| R _{DS(ON)} | Drain-Source On-State Resistance ^③ | V _{GS} =2.5V, I _D =6A | -- | 4.6 | 6.8 | mΩ |
| Dynamic Electrical Characteristics @ T_c = 25°C (unless otherwise stated) | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} =15V, V _{GS} =0V, f=1MHz | -- | 4380 | -- | pF |
| C _{oss} | Output Capacitance | | -- | 490 | -- | pF |
| C _{rss} | Reverse Transfer Capacitance | | -- | 440 | -- | pF |
| R _g | Gate Resistance | | -- | 2.8 | -- | Ω |
| Q _g | Total Gate Charge | V _{DS} =15V, I _D =10A, V _{GS} =4.5V | -- | 43 | -- | nC |
| Q _{gs} | Gate-Source Charge | | -- | 11 | -- | nC |
| Q _{gd} | Gate-Drain Charge | | -- | 13 | -- | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-on Delay Time | V _{DD} =15V, I _D =10A, R _G =6.8Ω, V _{GS} =4.5V | -- | 11 | -- | nS |
| t _r | Turn-on Rise Time | | -- | 15 | -- | nS |
| t _{d(off)} | Turn-Off Delay Time | | -- | 85 | -- | nS |
| t _f | Turn-Off Fall Time | | -- | 25 | -- | nS |
| Source- Drain Diode Characteristics @ T_c = 25°C (unless otherwise stated) | | | | | | |
| V _{SD} | Forward on voltage | I _{SD} =20A, V _{GS} =0V | -- | 0.73 | 1.2 | V |
| t _{rr} | Reverse Recovery Time | T _J =25°C, I _{SD} =20A, V _{GS} =0V | -- | 19 | -- | nS |
| Q _{rr} | Reverse Recovery Charge | di/dt=500A/μs | | 41 | | nC |

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.3mH, R_G = 25Ω, I_{AS} = 15A, V_{GS} = 10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.

Typical Characteristics

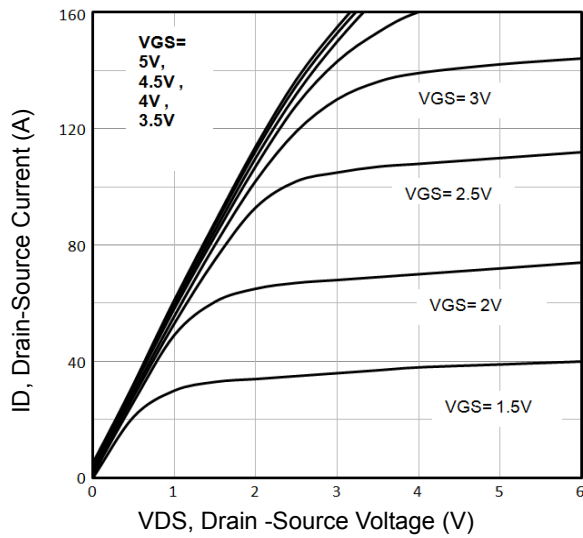


Fig1. Typical Output Characteristics

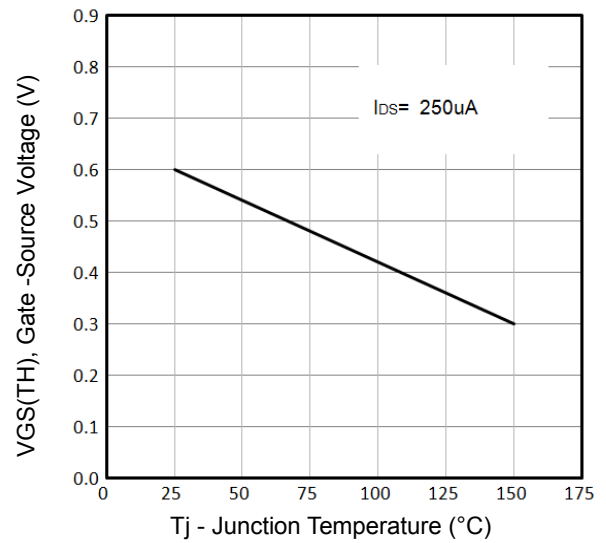


Fig2. $V_{GS(TH)}$ Gate -Source Voltage Vs. T_j

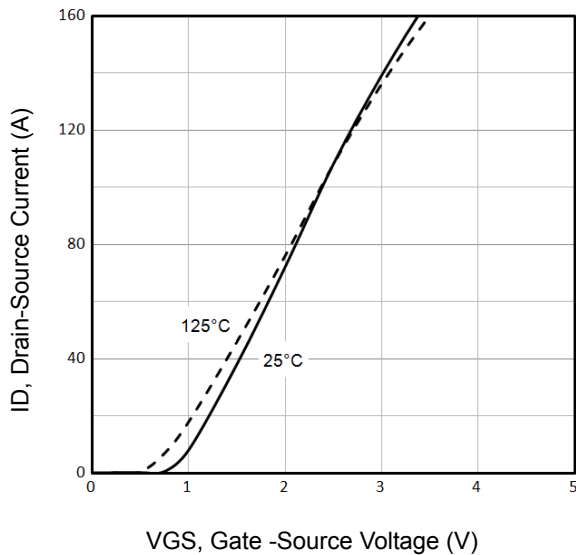


Fig3. Typical Transfer Characteristics

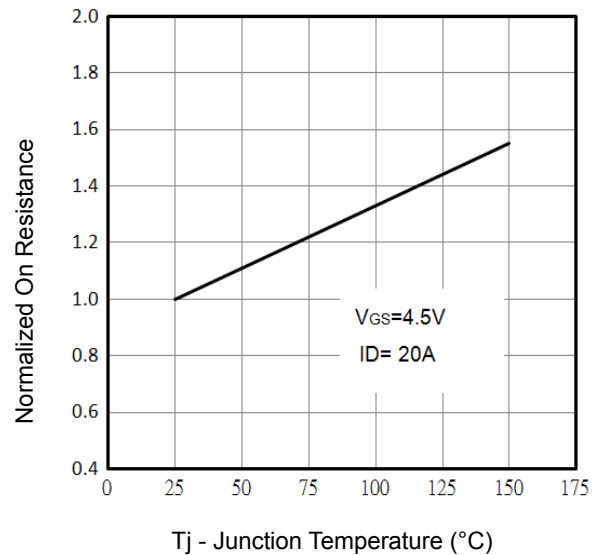


Fig4. Normalized On-Resistance Vs. T_j

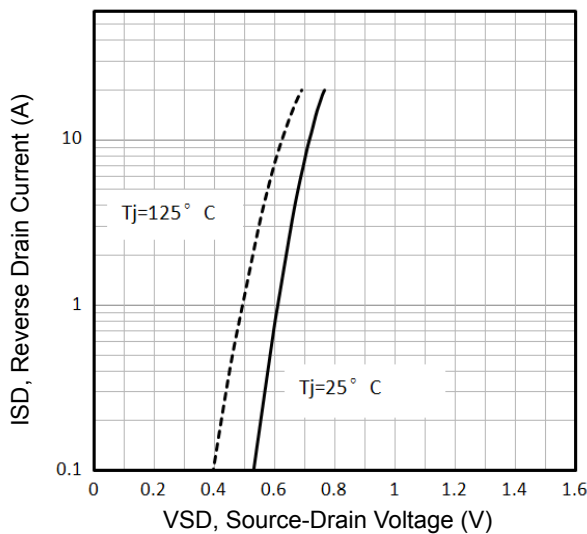


Fig5. Typical Source-Drain Diode Forward Voltage

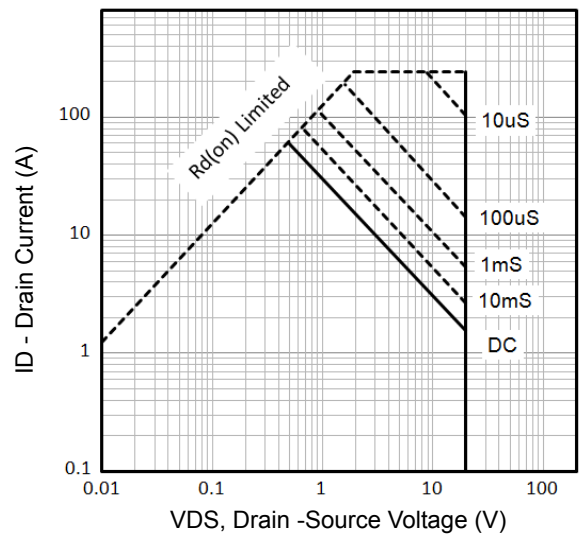


Fig6. Maximum Safe Operating Area

Typical Characteristics

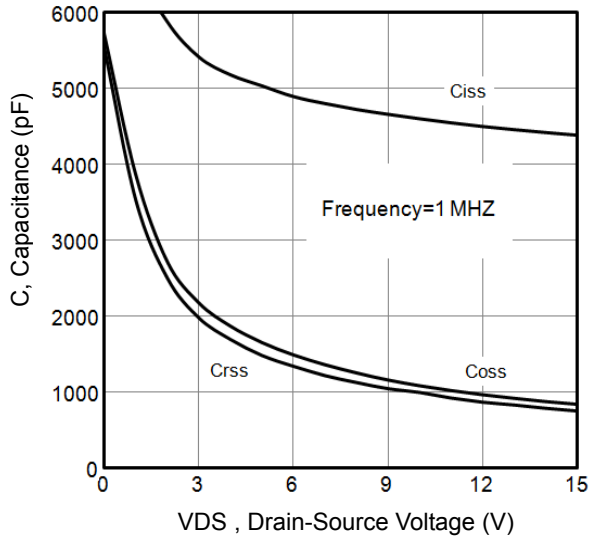


Fig7. Typical Capacitance Vs.Drain-Source Voltage

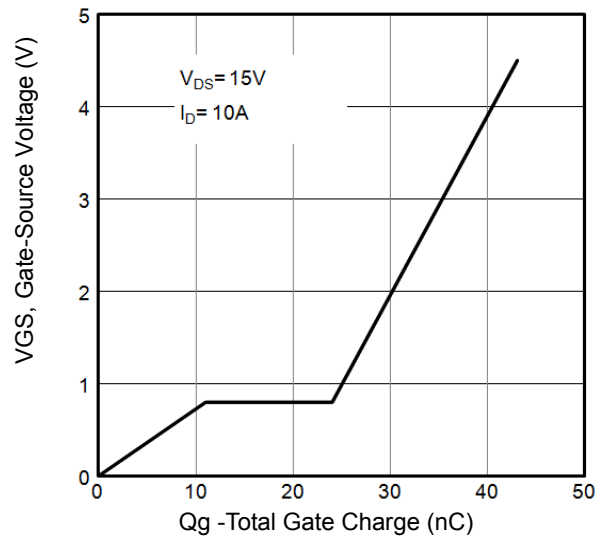


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

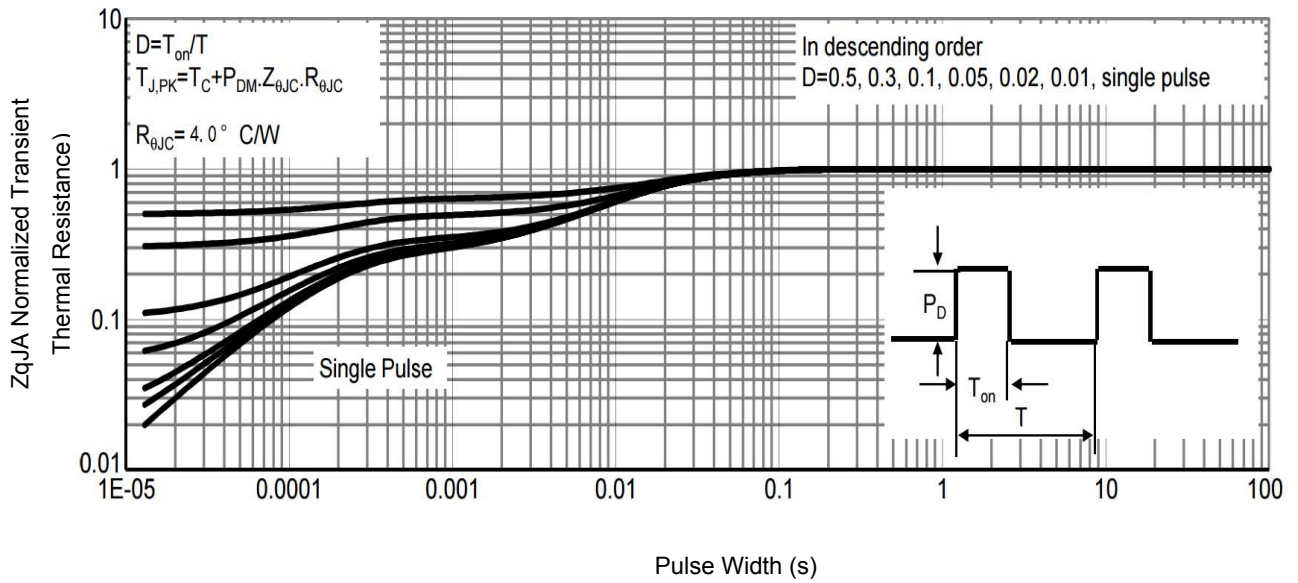


Fig9. Normalized Maximum Transient Thermal Impedance

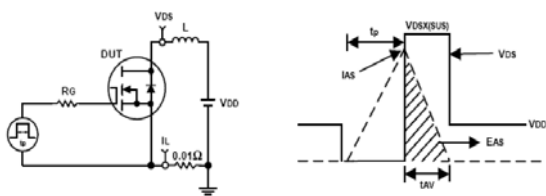


Fig10. Unclamped Inductive Test Circuit and waveforms

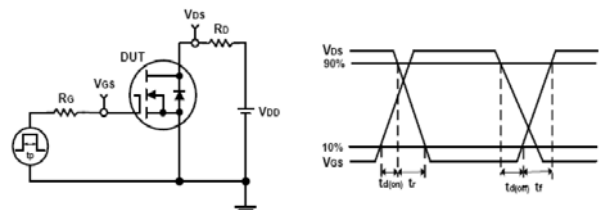
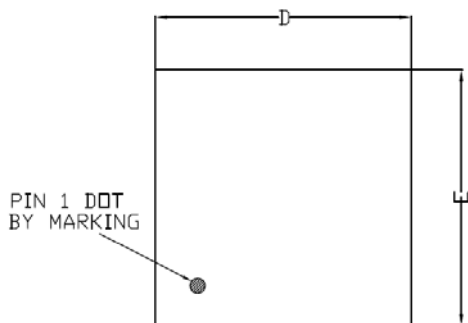
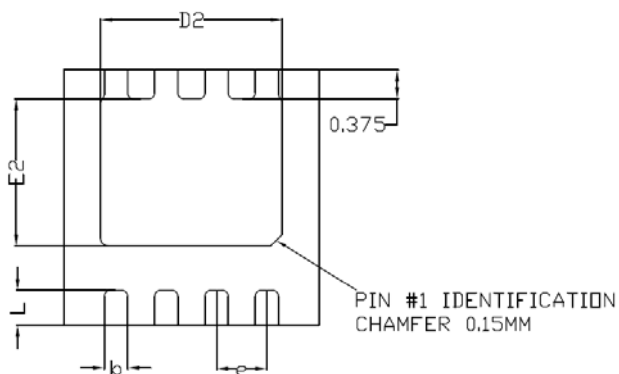


Fig11. Switching Time Test Circuit and waveforms

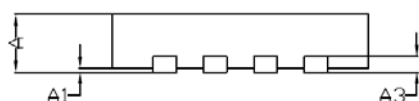
TDFN3.3x3.3 Package Outline Data



TOP VIEW



BOTTOM VIEW



SIDE VIEW

Lead finish : NiPdAu

DIMENSIONS (unit : mm)

| Symbol | Min | Typ | Max | Symbol | Min | Typ | Max |
|--------|----------|------|------|--------|----------|------|------|
| A | 0.70 | 0.75 | 0.80 | A1 | 0.00 | -- | 0.05 |
| A3 | 0.20 REF | | | D | 3.25 | 3.30 | 3.35 |
| E | 3.25 | 3.30 | 3.35 | D2 | 2.30 | 2.35 | 2.40 |
| E2 | 1.85 | 1.90 | 1.95 | b | 0.25 | 0.30 | 0.35 |
| L | 0.35 | 0.45 | 0.55 | e | 0.65 BSC | | |
| | | | | | | | |

Customer Service

Sales and Service:

Sales@vgsemi.com

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: www.vgsemi.com